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Product	Description
Custom Backplane/ Midplane Assemblies	 Backplanes with 40+ layers with design support for 25Gbs system requirements Support all Molex and industrystandard backplane connector systems (Impact[™], I-Trac[™], GbX[®], VHDM[®], VHDM-HSD[™], Milli-Z[™], µTCA, Serial ATA, SCSI, etc.) Mechanical and electrical design, development, simulation, test and in-house functional test design and development capabilities Global manufacturing footprint
MicroTCA Assemblies	 Molex 10 Gbps backplane design allows direct comparison of the Molex solution against any other backplane solution in a similar card edge by functionally evaluating the systems and comparing results, especially when higher speeds are required Backplane is supported by electrical models and empirical testing supporting 10 Gbs performance in an off the shelf solution Utilized Molex press fit connector technology to provide a high level of reliability from an fully integrated interconnect solution from Molex
LED Assemblies	 Experts in LED interconnect PCB assembly solutions: rigid board and flex configurations Molex facilities are TS 16949 certified for automotive LED board manufacturing cards Global manufacturing, material sourcing, tooling and testing capabilities Clean sheet mechanical and electrical design, development and test support, including circuit design and customer functional test design and development Mechanical packaging expertise to recommend interconnect solutions or to develop customer interconnects to fit your needs

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Product	Description
Media Connectivity Modules (MCM)	 Complete mechanical, electrical and design and process verification support Expertise in signal integrity engineering Cost effective solution by integrating Molex interconnect technology and manufacturing Currently serving customers worldwide, reliably and competitively Global footprint for manufacturing, engineering and customer support Designs supporting USB 3.0, HDMI, analog video and audio, Blue Tooth, 1394, Display Port, Ethernet
High Performance I/O Ports	 Digital, analog and power interconnect solutions SFP/SFP+ and QSFP products for ATCA and µTCA platforms Designs that support unitized multiport connections to simplify assembly, save space and reduce costs Signal integrity support to assure performance in high bandwidth applications Mechanical design support for custom bezels and sealed I/O port requirements
Interconnect Boards	 Value add service to our customers Utilize Molex connector technology to provide total Molex interconnect solution SMT, BGA, through hole, press fit and selective soldering processing capabilities Global manufacturing footprint Global supply chain support